

News Release

December 1, 2006

**Sales of “UF3000EX” 300mm
Final Generation Wafer Prober Commence**

Tokyo Seimitsu Co., Ltd. (President, CEO & COO: Sadakatsu Suzuki) is going to exhibit its state-of-the-art 300mm wafer prober, the UF3000EX at its booth (Small No. 5C-909) at “Semicon Japan 2006” (Dec. 6 – 8 in Makuhari Messe International Exhibition Hall 5) starting from Dec. 6, and begins sales of them.

Tokyo Seimitsu has continued to lead the semiconductor industry as the world’s top manufacturer of wafer probing machines. The UF3000EX is based on design concepts that transcend conventional norms and ideas, facilitating probing at high precision and high quality for testing of both high-end memory and logic devices. Furthermore, this fully automatic prober has been developed with the precision and basic performance that can be applied to the final generation of 300mm wafer size, making it an extremely effective investment. The features are outlined below.

UF3000EX Features

1. The combination of high-speed wafer handling made possible with new algorithms and high-speed, quiet direct-drive X-Y stage achieve extraordinary high throughput.
2. The Z stage that influences probing contact performance provides the world’s top level of load bearing capability for high pin count testing and high precision positioning, suitable for the age of full contact probing to shorten testing time.
3. An optimum topology structure design exhaustively eliminates positioning error of the wafer stage and provides best contact.
4. Provided enhanced inspection functions, flexibility to high/low temperature testing environments and other features.
5. A 15-inch color display enhances screen visibility, and ease of operation has also been dramatically enhanced by color wafer alignment image / very high magnification optics, wafer handling navigation and other features.

